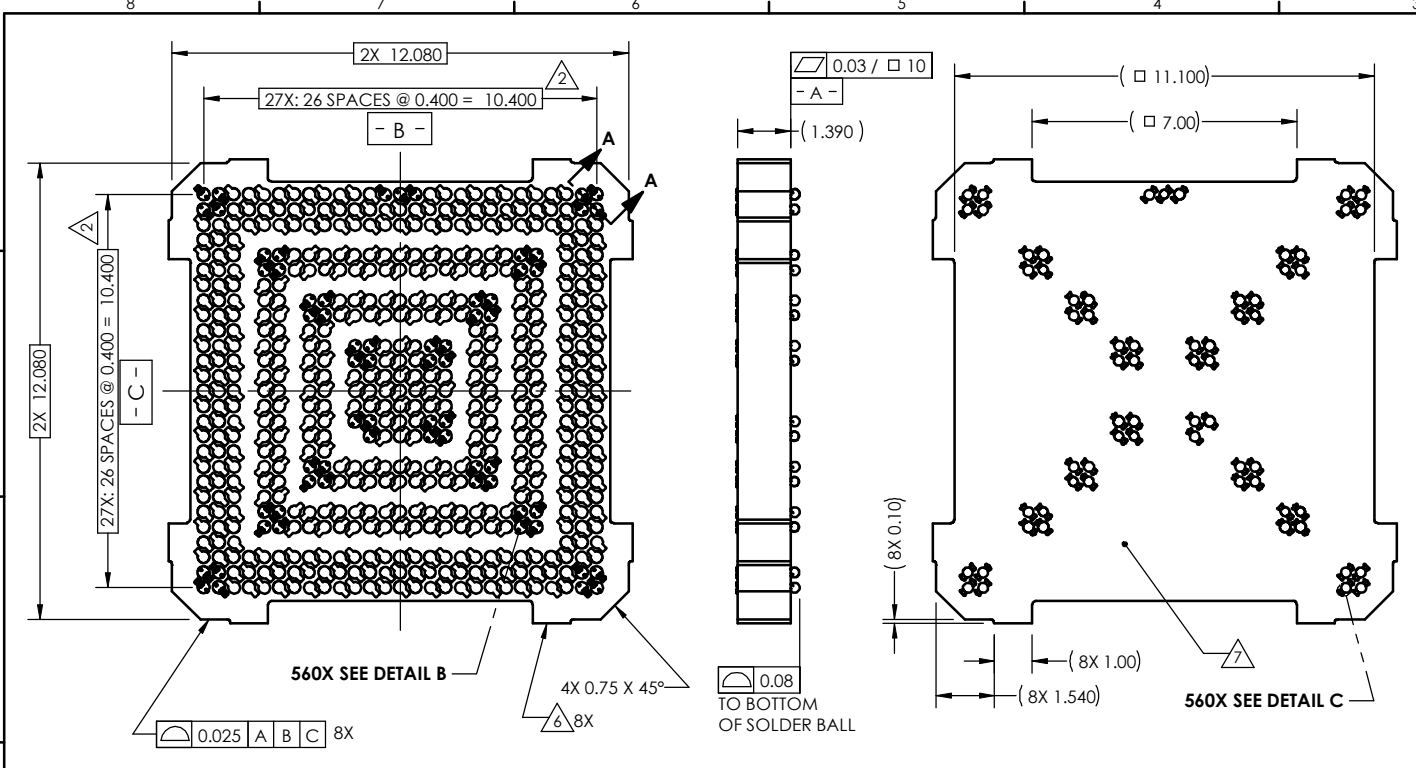
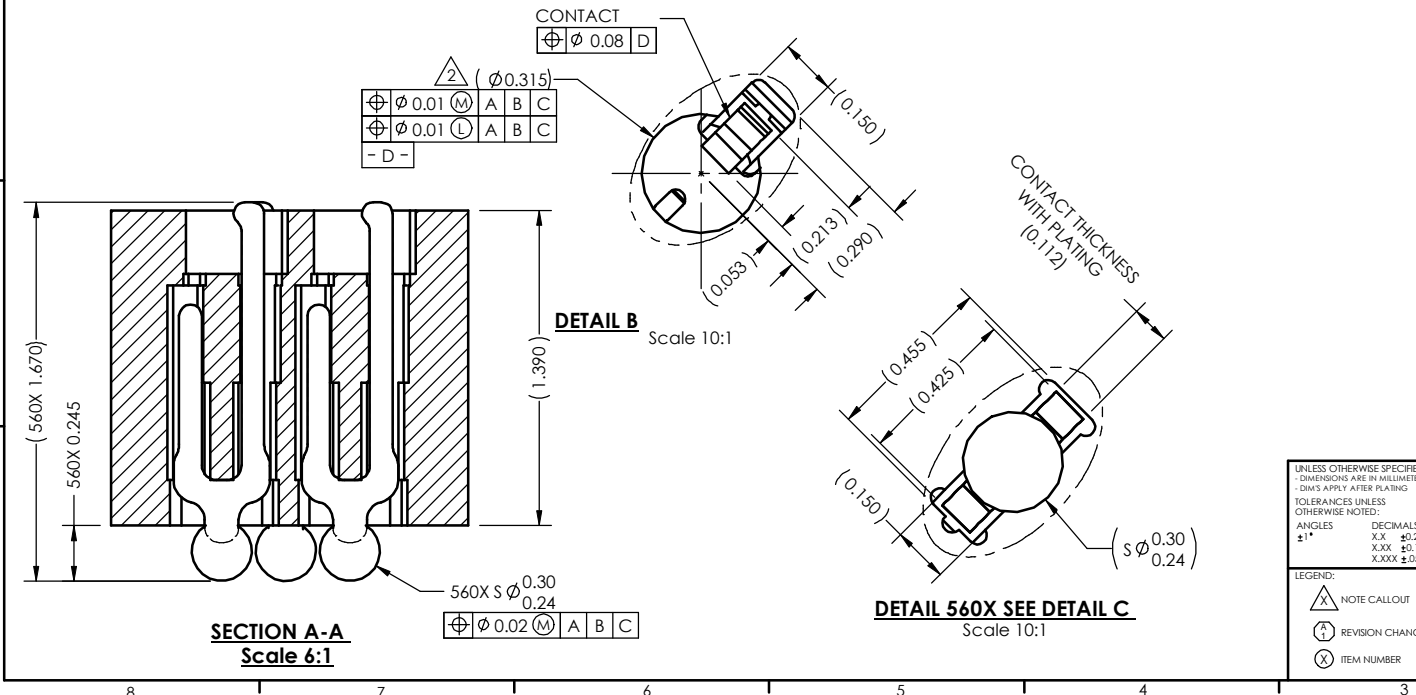


REV	ECO	BY	DESCRIPTION	APV	DATE
A	30013	CW	Initial Design	MP	12/03/09



Notes:

- Reference Cascade Microtech specification 103862-0004 for solder attachment.
- Dimension locates center of the contacts/slots.
- Reference Cascade Microtech specification 103863-0001 for application notes.
- Socket is designed for Qualcomm package as defined on package outline drawing (POD) NT90-VK846-1 Rev A.
- Datums B and C are determined by $\phi 0.315$ openings on corner slots.
- Tooling marks permitted. Maximum 0.10 protrusion (shown).
- Most slots not shown for clarity and file size.



Parts List			
Item	Qty	Part Number	Description
-	-	107140-0003	SCKT, 560G4012-0.40
-	-	103864-0002	PRESS, DEVICE INS, GRYP 12 X 12 (SOLD SEPARATELY)
-	-	105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
1	1	107141-0003	CS, 560G4012-0.40 W/SOLDER BALLS
1.1	1	107143-0003	HSG, 560G4012-0.40
1.2	560	104468-0014	CONTACT, G40, HALF, $\phi 0.25$, TIN, 0.1016

UNLESS OTHERWISE SPECIFIED:
 DIMENSIONS ARE IN MILLIMETERS
 DIMS APPLY AFTER PLATING
 TOLERANCES UNLESS OTHERWISE NOTED:
 ANGLES DECIMALS
 ±1° XX ±0.25
 XXX ±0.10
 XXXX ±0.50

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CAD GENERATED DRAWING
 DO NOT MANUALLY UPDATE

7115 NORTHLAND TERRACE SUITE 400
 BROOKLYN PARK, MN 55428
 (763) 509-0066

DRAWING APPROVALS

NAME	DATE
C. Wymer	12/02/09
M. Peery	12/04/09

THIRD ANGLE PROJECTION

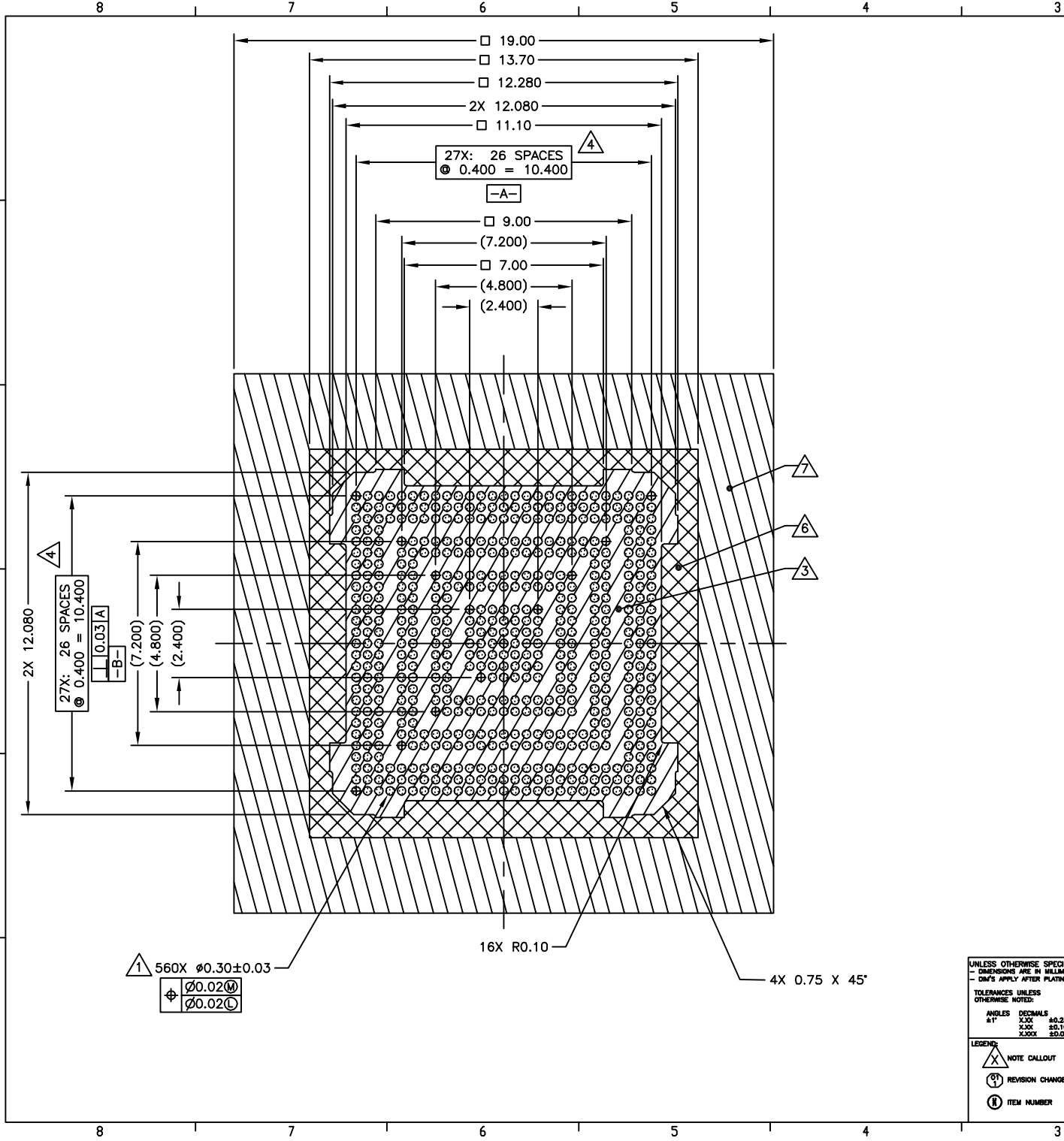
LEGEND:
 NOTE CALLOUT
 REVISION CHANGE
 ITEM NUMBER

CASCADE MICROTECH

SCKT, 560G4012-0.40 W/SOLDER BALLS

SCALE: C SOLIDWORKS
 MATERIAL: SEE BOM
 SHEET: 1 of 2

REV	ECO	BY	DESCRIPTION	APV	DATE
A	30013	CW	Initial Release	MP	12/04/09



NOTES:

- 1 Pad plated 100 micro inches solder minimum over copper base metal. Pads to be flat and coplanar ($\Delta 0.03$), free of burrs, solder, solder mask, silk-screen, ect.
2. Unless otherwise noted, all features located $\Phi 0.10 | A | B$
- 3 This surface to be flat with solder mask / silk-screen no more than 0.05 mm above the surface of the plated pads.
- 4 Locates center of pad/pattern.
5. The view shown is the top (connector side) of the board (looking through the connector).
- 6 Component placement area. Recommended no components. Please notify Cascade Microtech if unable to meet these recommendations.
- 7 Component placement area. Recommended max height 0.70. Please notify Cascade Microtech if unable to meet these recommendations.

UNLESS OTHERWISE SPECIFIED - DIMENSIONS ARE IN MILLIMETERS - DIM'S APPLY AFTER PLATING		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF CASCADE MICROTECH, INC. ANY REPRODUCTION IN PART OR WHOLE WITHOUT THE WRITTEN PERMISSION OF CASCADE MICROTECH, INC. IS PROHIBITED.	
TOLERANCES UNLESS OTHERWISE NOTED:		7115 NORTHLAND TERRACE SUITE 400 BROOKLYN PARK, MN 55428 (763) 509-0066	
ANGLES DECIMALS ±1"	X/30 ±0.25 X/30 ±0.10 X/30 ±0.050	CAD GENERATED DRAWING DO NOT MANUALLY UPDATE	
LEGEND:		DRAWING APPROVALS	
△	NOTE CALLOUT	NAME	DATE
Ⓜ	REVISION CHANGE	C. Wymer	12/03/09
Ⓡ	ITEM NUMBER	M. Peery	12/04/09
THIRD ANGLE PROJECTION		TITLE	
		SPEC, PCB, 560G4012-0.40	
SCALE		CAD FILE	ISSUES
1:1		AUTOCAD	104311-0188
SHEET		REV	A
1 of 1			